



BEST AVAILABLE COPY

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Do not enter
EX 6/12/03

In re Application of:

Akram et al.

Serial No.: 09/241,177

Filed: February 1, 1999

For: HIGH DENSITY MODULARITY FOR
IC'S

Examiner: C. Novacek

Group Art Unit: 2822

Attorney Docket No.: 3638US
(98-0093.00/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

May 19, 2003
Date

Signature

Deidra Pfeil
Name (Type/Print)

16# / Amdt
Dug
6/4/03
N. Kim

AMENDMENT UNDER 37 C.F.R. § 1.116

Box AF
Commissioner for Patents
Washington, D.C. 20231

Sir:

This amendment is in response to the final Office Action of March 19, 2003 whose initial period of response is set to expire on June 19, 2003.

RECEIVED
MAY 27 2003
TECHNOLOGY CENTER 2800